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(54) **PACKAGE STRUCTURE**

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ABSTRACT

A package structure includes a substrate having a bearing surface, an electronic component disposed on the bearing surface and having a first height, at least one heat conductor disposed on the bearing surface and having a second height, an encapsulant disposed on the bearing surface and having a side covering the electronic component and the at least one heat conductor and a third height, and a heat dissipation structure disposed on the encapsulant. The third height is greater than or equal to the first height and the second height. A surrounding area where the substrate is in contact with the electronic component is a heat-generating area, and the at least one heat conductor is disposed in the heat-generating area.

